IN THE CLAIMS

Please Amend Claim 1 as follows:

1. (Currently Amended) A method for connecting a connecting surface of a first silicon wafer with a connecting surface of a second silicon wafer so as to form an insulated cavity after assembly, at least one of the two silicon wafers including at least one functional area intended to be within the cavity, said method being characterized in that it includes the steps of:

- depositing a first group of alloy soldering bumps on the connecting surface of the first silicon wafer, ~~the~~ said first group of ally soldering bumps being separated from one another by an even distance which is sufficiently small to cause joinings during the assembly of the two silicon wafers, the said deposition of the soldering bumps being carried out during the step of depositing the soldering bumps intended for the electrical contacts,

- depositing a second group of alloy soldering bumps on the connecting surface of the first silicon wafer, said second group of ally soldering bumps being separated from one another by an distance which is sufficiently large to prevent joinings during the assembly of the two silicon wafers, and

- reflux soldering in order to connect the two silicon wafers by melting of the alloy soldering bumps.

2. (Original) A method as claimed in Claim 1, also including a step of applying a resin to the contour of the cavity.

3. (Previously Presented) A method as claimed in Claim 1, for which the two silicon wafers include functional etchings.

4. (Previously Presented) A method as claimed in Claim 1, characterized in that it includes a step of filling the cavity with an inert gas.

5. (Previously Presented) A method as claimed in Claim 1, characterized in that it is implemented within an enclosure filled with an inert atmosphere.

6-8 (Cancelled).